

Hermetic Seal Launchers

HERMETIC SEAL DATA

MATERIALS

All metal parts: Kovar, gold-plated per MIL-G-45204 type II, grade C, class 1 over nickel per MIL-C-26074, class 1, over copper per MIL-C-14550

Glass: Corning glass as noted:

P/N	Glass
920-55	7052
920-56	7070
920-69	7052
920-82	7070
920-92	7052

Hermeticity: Greater than 1×10^{-8} cc/sec at 1 atmosphere

Impedance: 50 ± 1 ohms

Frequency range: DC-26 GHz

Insertion loss:

0.1 dB max to 12.4 GHz

0.2 dB max to 18 GHz

0.25 dB max to 26 GHz

VSWR: Dependent on application

Rated voltage: 335 VRMS max at sea level

Rated current: 500 mA

DWV: 1,000 VRMS at sea level

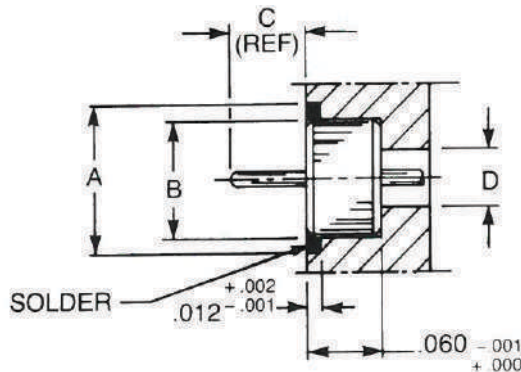
Insulation resistance: 100 kMΩ (25°C)

Solderability: Per MIL-STD-202, method 209

Meniscus: 0.005" max

Pin concentricity: 0.003 T.I.R.

Temperature range: -65°C to 250°C



MOUNTING DIMENSIONS

P/N	A (+0.001)	B (+0.001)	C
920-55	0.127	0.102	0.070
920-56	0.140	0.115	0.070
920-69	0.188	0.163	0.060
920-82	0.127	0.102	0.070
920-92	0.188	0.163	0.075

- 1) The hermetic seal should be as flush as possible with the surface of the package. When the seal is recessed into the mounting hole, an air gap is created which adversely affects electrical performance. A slight protrusion (less than 0.005") is acceptable.
- 2) A solder ring should be used which will fill the counterbore flush with the package surface after soldering. The counterbore can be an 80° to 90° countersink rather than square-bottomed as shown, but still must be filled to avoid an air gap.
- 3) Some users, especially when using a small pin diameter and a thick-walled package, use a Teflon insulator in the package wall to support the pin. The through-hole diameters shown below are for 50 ohm impedance.

Pin Ø	"D" Air Dielectric	"D" Teflon Dielectric
0.012	0.028	0.040
0.015	0.035	0.050
0.018	0.041	0.059
0.020	0.046	0.066